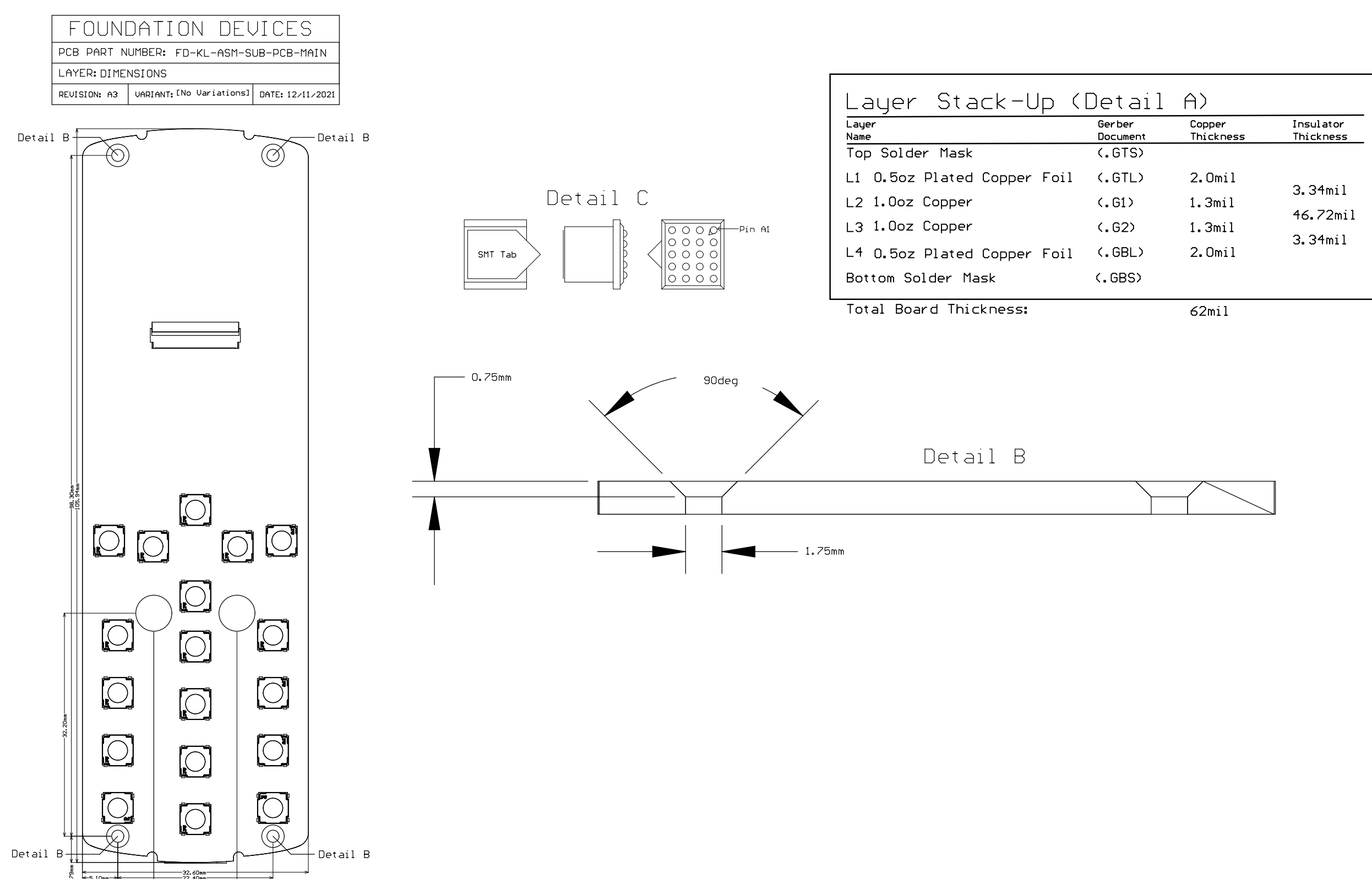


NOTES: (UNLESS OTHERWISE SPECIFIED)

1. THIS DRAWING SPECIFIES THE REQUIREMENTS FOR A PRINTED CIRCUIT BOARD IN ACCORDANCE WITH SPECIFICATION IPC-6012 CLASS 2 (LATEST REVISION).
2. THE PCB MUST BE LEAD FREE ASSEMBLY PROCESS COMPATIBLE AND MUST BE ABLE TO HANDLE A MINIMUM OF 5 CYCLES AT 260 DEGREES CELSIUS FOR 10 SECONDS.
3. BASE MATERIAL - LAMINATE AND PREPREG SHALL MEET IPC-4101E/124 or /129
  - TG: MUST BE GREATER THAN OR EQUAL TO 150 DEGREES CELSIUS.
  - TD: MUST BE GREATER THAN OR EQUAL TO 325 DEGREES CELSIUS.
4. COPPER FOIL WEIGHT - SEE STACKUP DETAIL 'A'
  - PCB MANUFACTURER CAN REQUEST AN ALTERNATE STACKUP
  - ALTERNATE STACKUP MUST BE APPROVED IN WRITING BY FOUNDATION DEVICES
5. MINIMUM CONDUCTIVE WIDTH/SPACING TO BE 0.1mm/0.1mm
6. PLATING FINISH: ENIG
7. SOLDERMASK - TO MEET THE REQUIREMENTS OF IPC-SM-840E (OR LATEST REVISION).
  - BLACK COLOR. BOTH SIDES.
  - SOLDERMASK ON SOLDERABLE SURFACES IS PROHIBITED.
  - ALL CIRCUITRY DEFINED AS COVERED SHALL NOT BE EXPOSED.
8. SILKSCREEN - WHITE EPOXY OR ACRYLIC INK. BOTH SIDES. NO SILKSCREEN ON ANY EXPOSED COPPER FEATURE.
9. REMOVE ALL NON-FUNCTIONAL INNER LAYER PADS.
10. ELECTRICAL TEST - 100% IPCD356.
11. DFM CHECK MUST BE RUN ON BOARD DATA BEFORE BUILDING BOARDS.
  - UNLESS PRIOR APPROVAL IS GIVEN IN WRITING BY FOUNDATION.
12. TEARDROPS MAY BE ADDED AT THE FAB HOUSE TO ALL SIGNAL LAYERS.
13. VIA TENTING - ALL VIAS ON BOTH SIDES MUST HAVE TENTING.
14. FINISHED PCB THICKNESS IS CRITICAL: FROM L1 PAD TO L4 PAD TO BE 62mil +/- 10%
15. TWO SOLDER SAMPLES TO BE PROVIDED.
16. SUPPLIER MARKINGS - ON SECONDARY SIDE ONLY.
  - MUST BE UL RECOGNIZED AND MUST HAVE AN ID THAT CONFORMS TO UL94V-0
17. FINISHED PCB MUST BE PANELIZED FOR ASSEMBLY ACCORDING TO CONTRACT MANUFACTURER'S REQUIREMENTS.
18. MOUNTING HOLES WITH DIAMETER 1.75mm TO HAVE COUNTERSINKS ON PRIMARY SIDE.
  - LOCATIONS AND DIMENSIONS SHOW BY 'DETAIL B'.
19. CAMERA PIN-A1 LOCATION SHOWN IN 'DETAIL C'.

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A1	Release for Production.	11/22/2021	M. Beach
A2	Added and adjusted some test-points.	11/29/2021	M. Beach
A3	Added U1 LDO, C87-89, TP85. Removed R1, C1.	12/11/2021	M. Beach



LICENCE: CERN-OHL-S-2.0

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DRAWN BY M. Beach	FOUNDATION		Foundation Devices Inc. 6 Liberty Square #6018 Boston, MA 02109	
CHECKED BY M. Beach	PCB PART NUMBER: FD-KL-ASM-SUB-PCB-MAIN			
APPROVED ON 12/11/2021	SIZE C	DATE: 12/11/2021	VARIANT: [No Variations]	REV A3
	SCALE: 1/1	DO NOT SCALE DRAWING	SHEET 1 OF 1	